

	Type	Hits	Search Text
1	BRS	288	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and (etch\$3 plasma) and (nitrogen N2 "n.sub.2") and (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2")
2	BRS	18	((low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and (etch\$3 plasma) and (nitrogen N2 "n.sub.2") and (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2")) and etch\$3 same (low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) same ((nitrogen N2 "n.sub.2") with (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2"))

	DBs	Time Stamp	Comments	Error Definition	Errors
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/14 16:13			0
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/14 16:14			0